

# **Ensemble™ Essentials**

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**Ansoft Corporation**  
**Four Station Square, Suite 200**  
**Pittsburgh, PA 15219-1119 USA**  
**(412) 261-3200**  
**[www.ansoft.com](http://www.ansoft.com)**

**Ansoft Corporation**  
**3800 Arapahoe Avenue , Suite 250**  
**Boulder, CO 80303 USA**  
**(303) 541-9525**  
**[gray@ansoft.com](mailto:gray@ansoft.com)**



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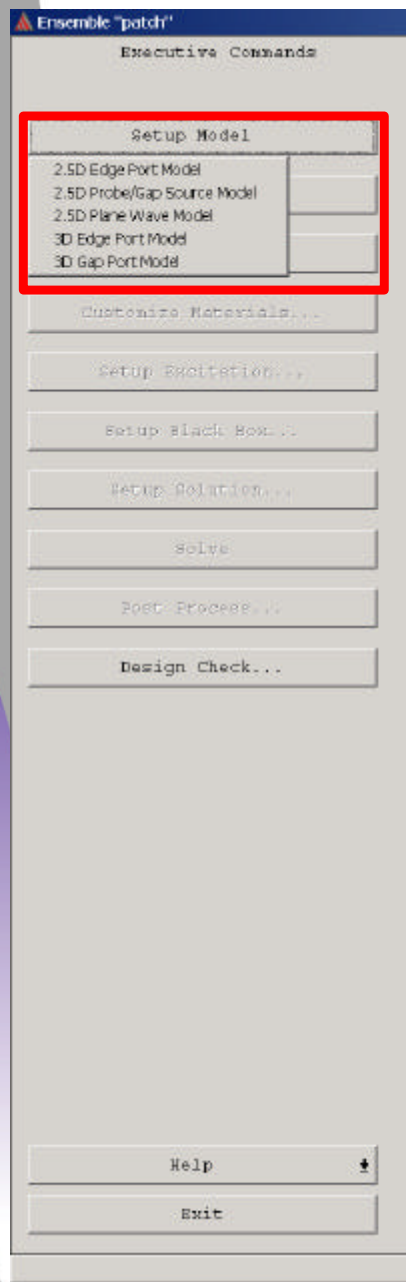
# **Ensemble™ Fundamentals Remain the Same ...**

**Independent of GUI !**



# Topics

- 2.5D and 3D Excitations
- Editing layers
- Layer types
- Importing/exporting DXF
- Arranging layers/specifying materials
- Creating vias
- Frequency sweeps
- Meshing
- Port solution
- Normalized & generalized S-parameters
- Accurately modeling thin layers
- Advanced solver options
- Environment variables



## 5 Excitation Types:

### ► 2.5D Edge Port (default choice)

- **Excitation parallel to trace/slot plane(s)**
- **High freq. (~>100MHz)/electrically larger geometries**
- **.7\*lambda de-embedding arms, compute S matrix from currents induced on arm**
- **Higher order modes ok**
- **2D mesh, metal thickness accounted for with Zs**
- **Orthogonal/cylindrical vias *only***

### ► 2.5D Probe/Gap Source

- **Coaxial probe perpendicular to signal plane**
- **Voltage Gap Sources**
  - **1Hz to occurrence of 1<sup>st</sup> higher order mode**
  - **1V at excited port, current computed at all ports (defines Y matrix)**
  - **No de-embedding arms/overlap issues**

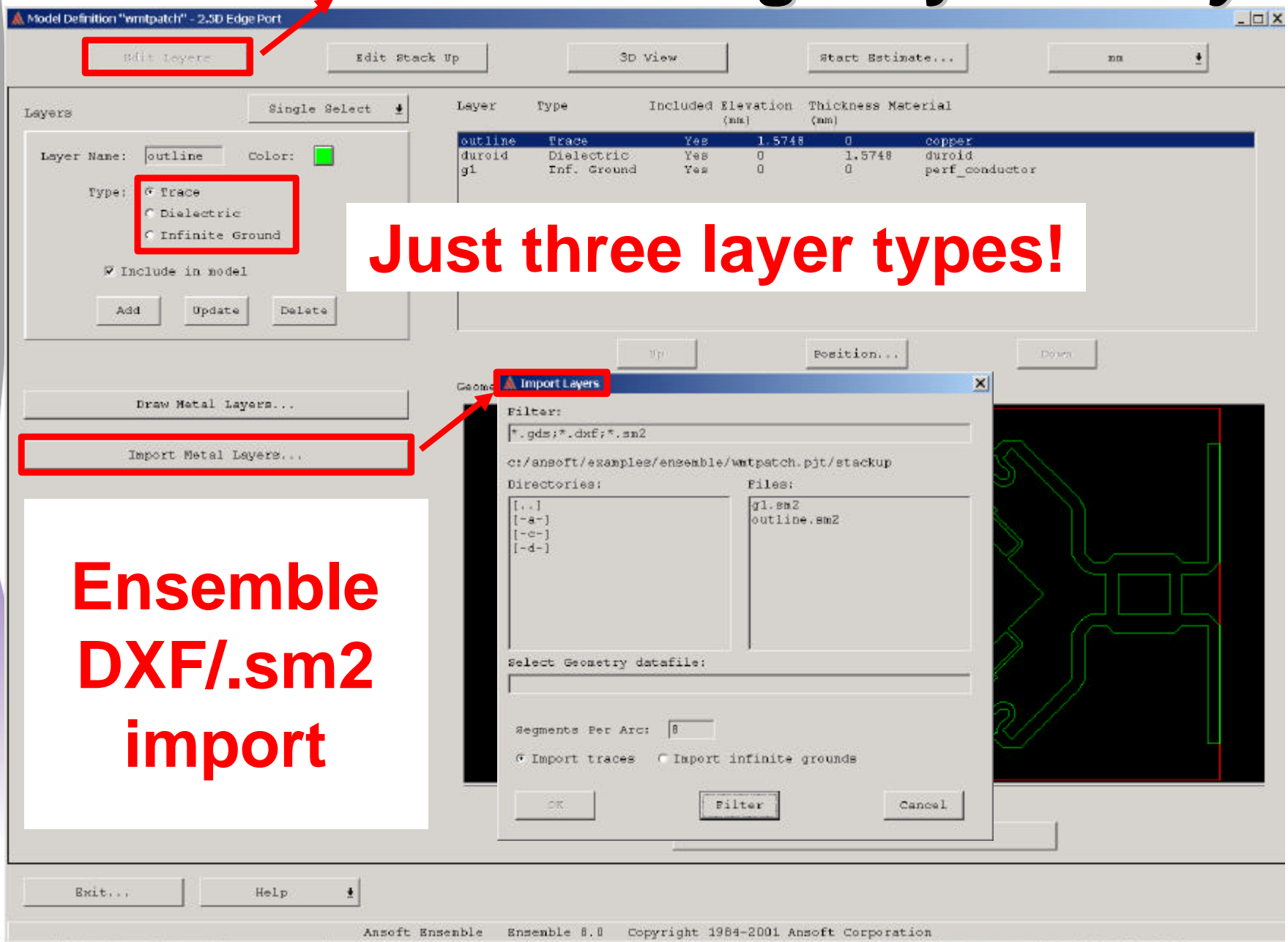
### ► 2.5D Plane Wave

- **RCS only**

### ► 3D Edge/Gap Port

- **3D ports similar to 2.5D (freqs., de-embed arms)**
- **Extra cost/licensed feature**
- **Metal thickness modeled using 3D surface mesh**
- **Non-cylindrical/orthogonal vias allowed**

# Create/remove/arrange layers *only*



**Just three layer types!**

**Ensemble  
DXF/.sm2  
import**

# Three Layer Types

## ▸ Trace

- All objects drawn on trace layers are metal
- To create an aperture drawn within a trace
  - Draw both objects
  - “Customize Materials” inner object to air

## ▸ Dielectric

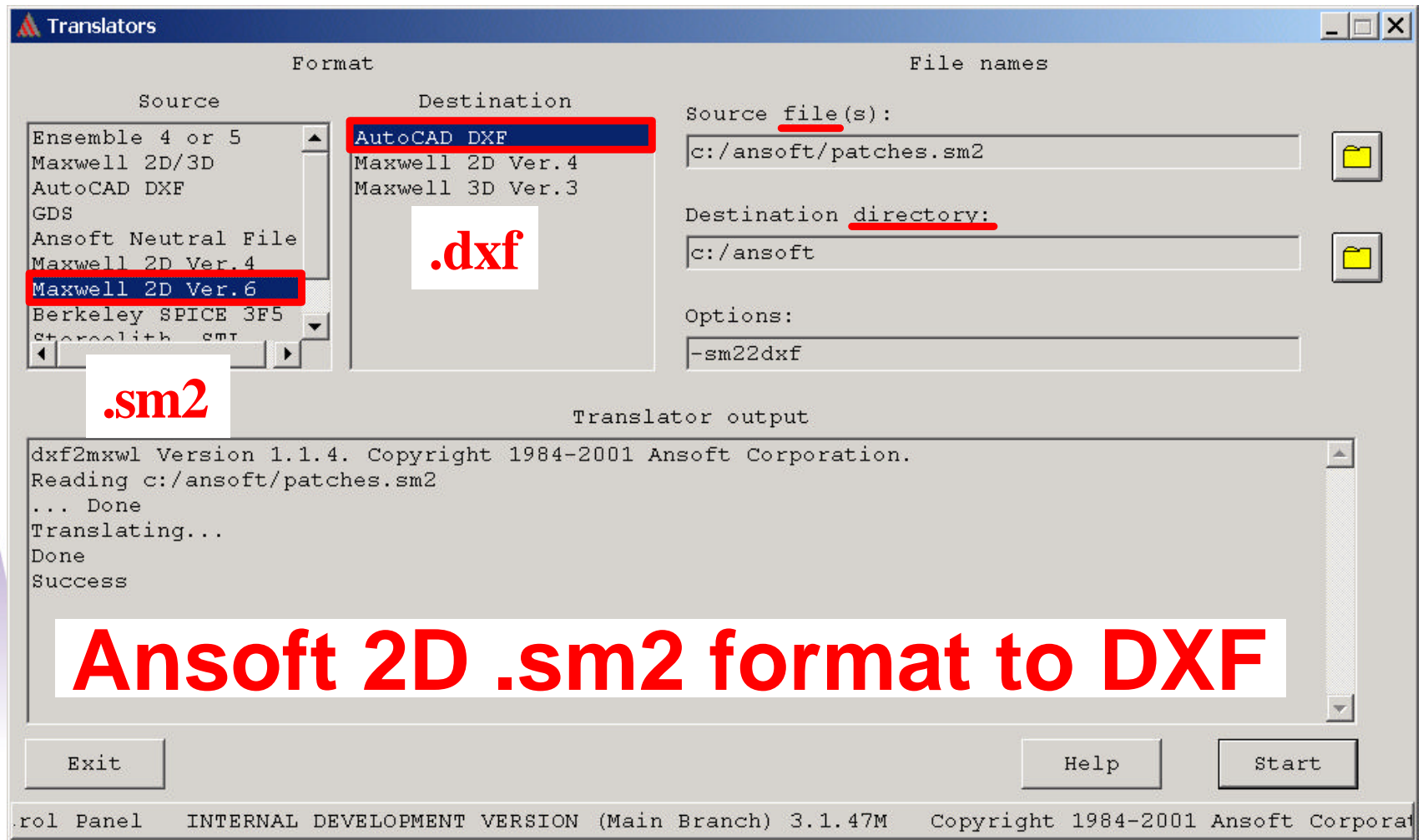
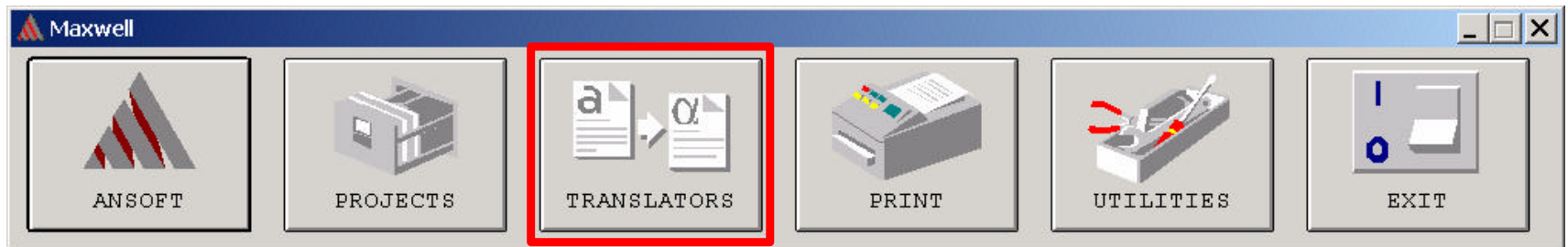
- Infinite in XY plane, finite in Z direction
- Infinite dielectric effects
  - Antenna patterns at horizon
  - Other finite dielectric effects not captured
- Elevation reference for Trace & Inf. Grounds
- Define first! (dielectrics are elevation reference)

## ▸ Infinite Ground

- Infinite in XY plane
- All objects drawn on inf. ground layers are slots
- To create a metal object drawn within a slot
  - Draw both objects
  - “Customize Materials” inner object to metal

# Importing/Exporting DXF

- ▶ **“Zero Width Closed Polylines” Only**
  - ▶ **No thick lines**
  - ▶ **Polyines begin and end at same point**
- ▶ **AutoCAD R14 DXF**

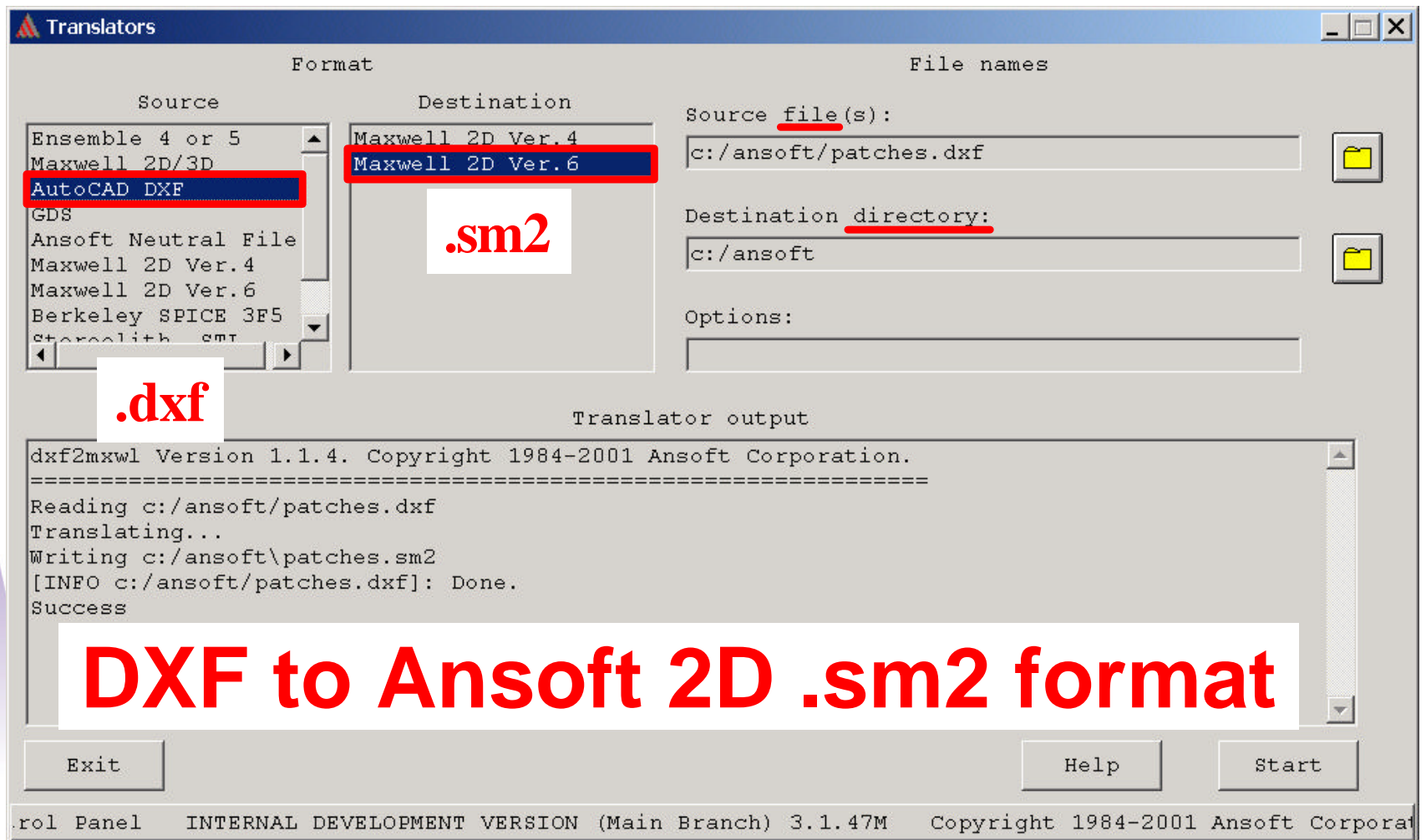
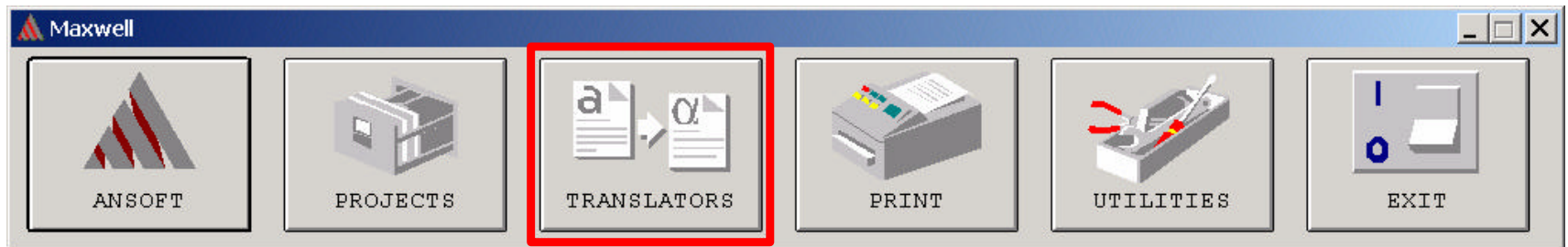


**Ansoft 2D .sm2 format to DXF**



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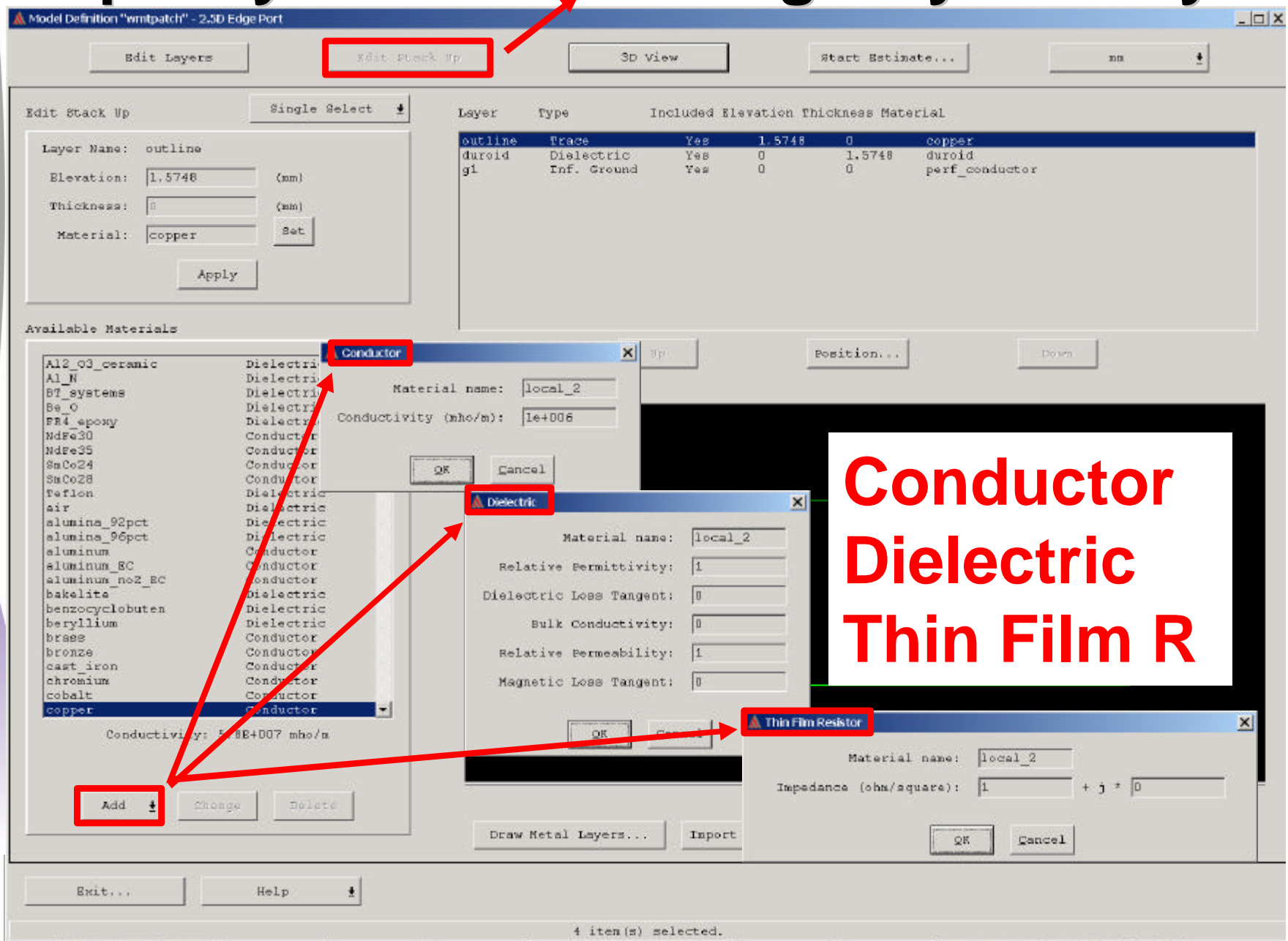


**DXF to Ansoft 2D .sm2 format**



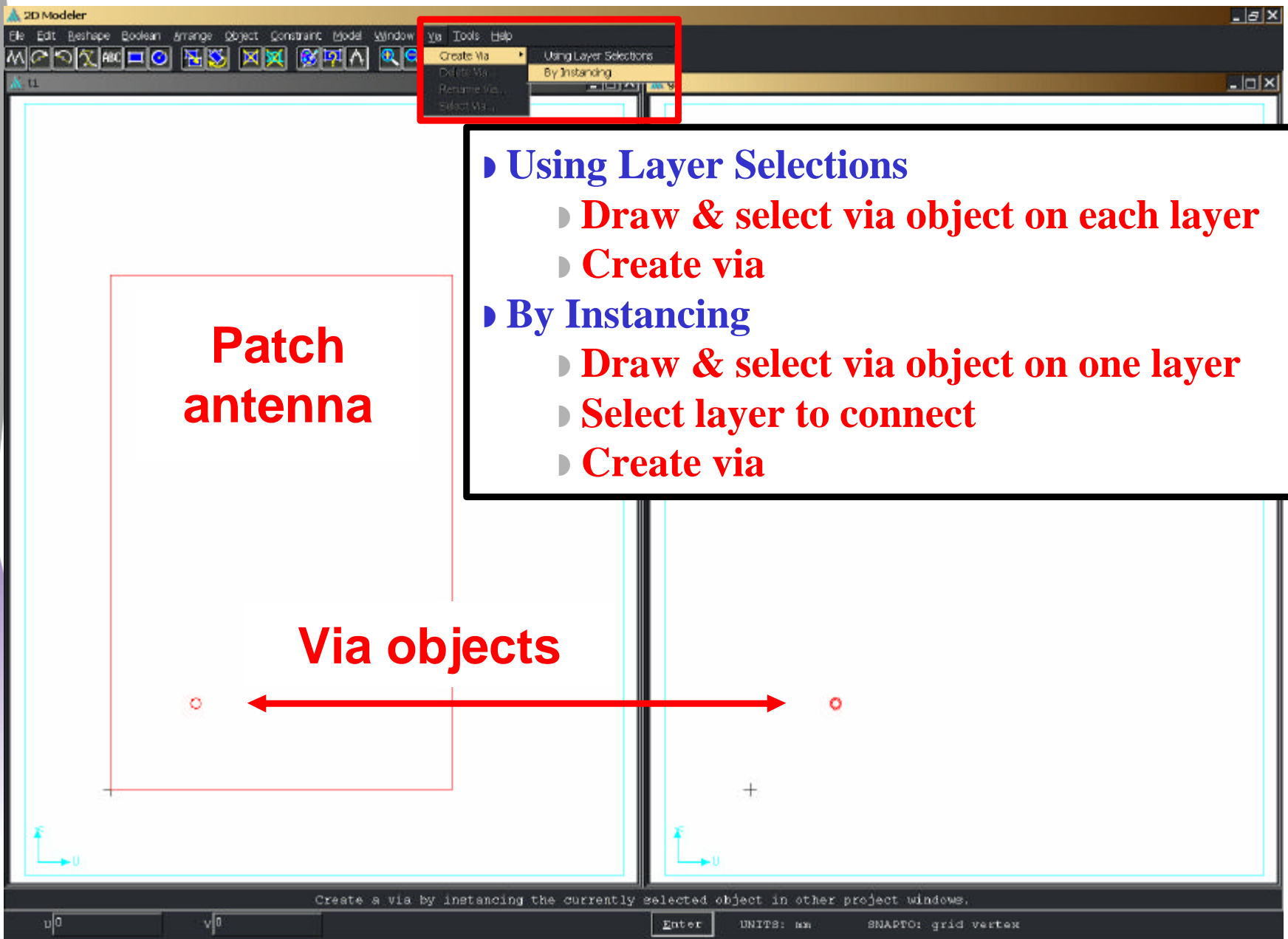
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# Specify materials/arrange layers only



**Conductor**  
**Dielectric**  
**Thin Film R**

# Creation of Vias



The screenshot shows the ANSOFT 2D Modeler interface. The 'Via' menu is open, highlighting 'Create Via' and 'By Instanting'. A red box highlights the 'Via' menu. Below the menu, a diagram shows a patch antenna (a red rectangle) and two via objects (red circles) connected by a red double-headed arrow labeled 'Via objects'. The status bar at the bottom indicates 'Create a via by instanting the currently selected object in other project windows.' and 'Enter'.

**2D Modeler**

File Edit Reshape Boolean Arrange Object Constraint Model Window

Via Tools Help

- Create Via
  - Using Layer Selections
  - By Instanting
- Delete Via...
- Rename Via...
- Select Via...

**Patch antenna**

**Via objects**

Create a via by instanting the currently selected object in other project windows.

u|0 v|0 Enter UNITS: mm SNAPPO: grid vertex

# 2.5D & 3D Vias

## ► 2.5D Vias

- **Cylindrical**
- **Induced currents are vertical**
- **Induced currents are circularly symmetric**

## ► 3D Vias

- **Arbitrary cross section**
- **Induced currents in any direction**
- **Meshed similar to other metal surfaces**

# Frequency Sweeps

## ► Fast Sweep

- **S-parameters only**
- **MoM matrix solved only at freqs. needed for interpolation**
- **Faster in general than Discrete for large number of freq. points**
- **No way to know in advance how long sweep will take**
- **Currents not saved**

## ► Discrete Sweep

- **MoM matrix solved at every freq.**
- **Currents may be saved/plotted**
- **Near/Far fields may be generated**
- **Solve time may be estimated**

# Meshing Guidelines

Mesh setup:      ☐ Initial      ☐ Previous      ☐ Current

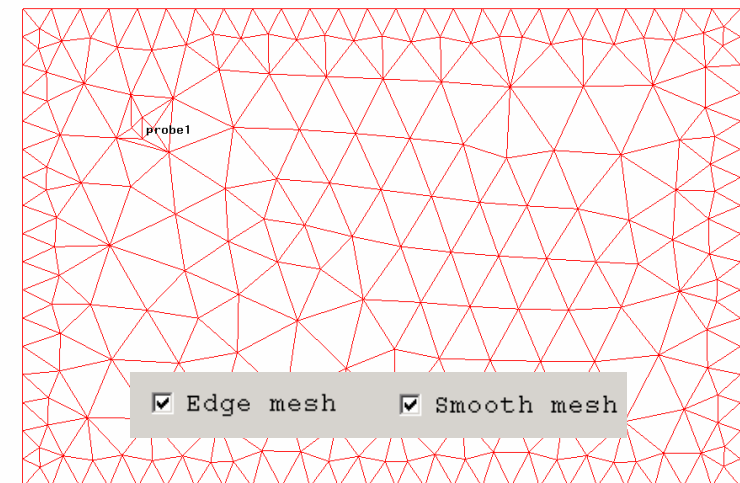
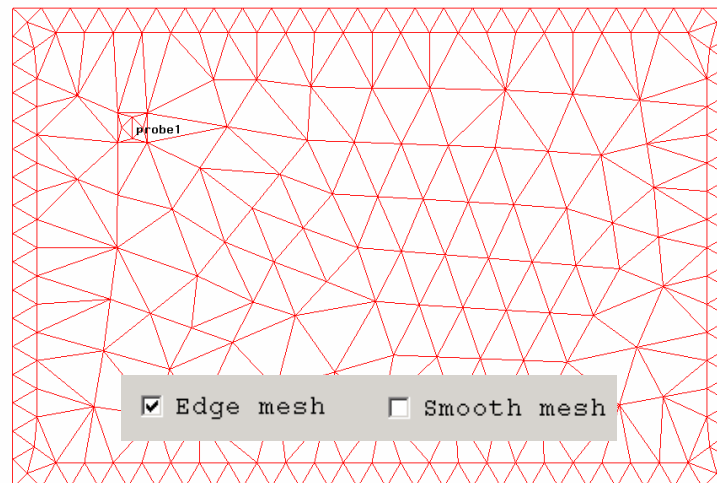
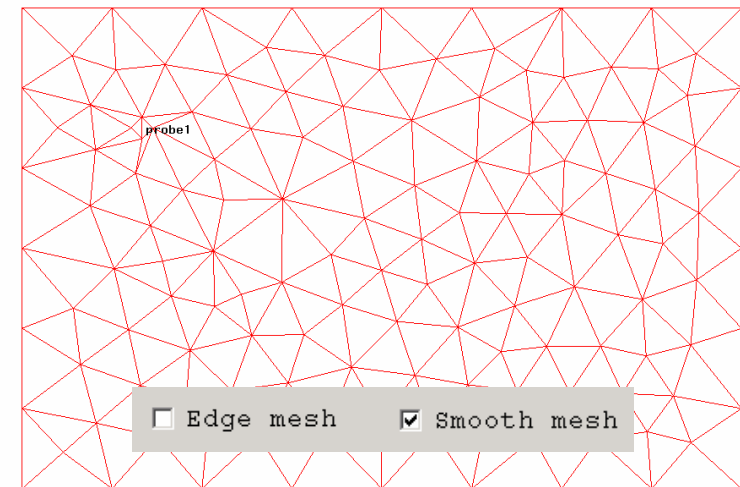
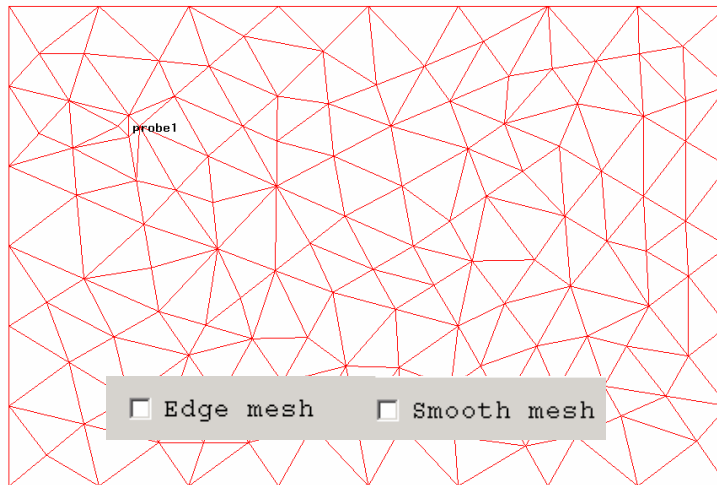
☒ Fixed      Frequency:

☐ Edge mesh      ☐ Smooth mesh

- ▶ Use Fixed mesh
- ▶ Use highest freq. of interest as starting point for mesh frequency
- ▶ Investigate effect, in band of interest (i.e. shift in resonance), of increasing mesh density
- ▶ Edge meshing/virtual objects\* may assist in capturing behavior, as currents flow along the edge of conductors
- ▶ **Poor mesh = poor result**  
**(“Garbage in, garbage out”)**



# Mesh Illustrations



# Port Solution

- ▶ Microstrip, Stripline:  $Z_0 = Z_{PI}$
- ▶ Slotline, CPW:  $Z_0 = Z_{PV}$
- ▶ Full-wave eigenvalue problem  
(includes dispersion)



# Normalized and Generalized S-Parameters

## ▸ Normalized

- $Z_0$  typically the same for all ports
- $Z_0$  typically 50 ohms
- $Z_0$  constant over frequency

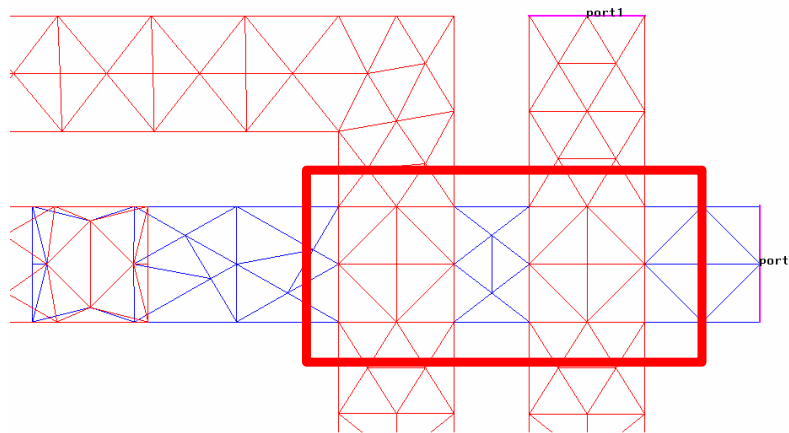
## ▸ Generalized

- Computed by default
- Each port may have different  $Z_0$
- $Z_0$  varies with frequency

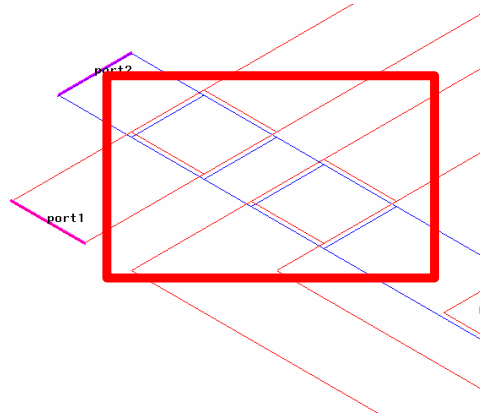
# Accurate Modeling of Thin Layers: Meshing and Trace Thickness

**Example:**  
**Spiral inductor**

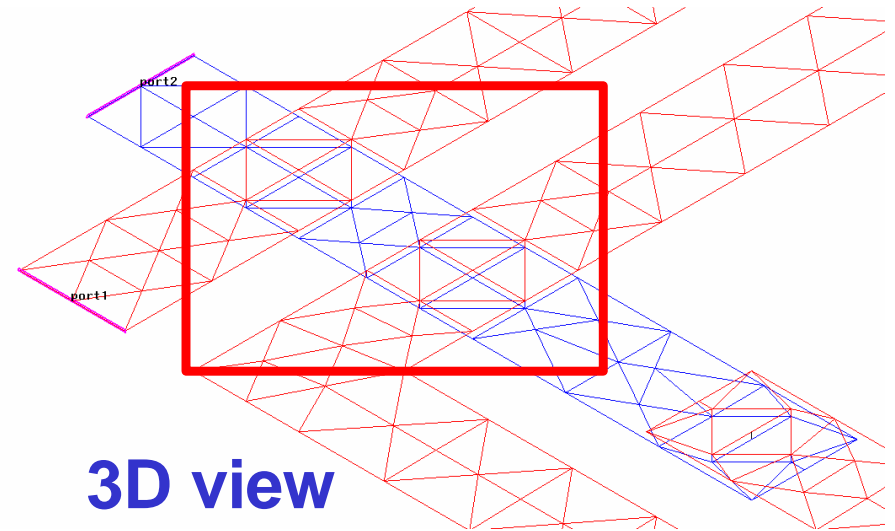
**mesh top view**



**Appropriately set**  
**ENSEMBLE\_TRACE\_THICKNESS\***



**Virtual objects force  
same mesh on both  
layers, improves  
calculation of current  
interactions**



**3D view**

# Advanced Solver Options I

## ▶ Loop Tree

- ▶ Utilized by default
- ▶ MoM matrix re-ordering
- ▶ Stabilizes calculations at very low frequencies

## ▶ Gap Port Calibration

- ▶ Eliminates mismatch between port and feedline
- ▶ Uses Through Reflect Line (TRL) method
- ▶ Provides most improvement at high frequency

## ▶ Accuracy Level

- ▶ Adjusts accuracy of MoM integrals, port solver, and matrix resolution
- ▶ Default is lowest setting of 1

# Advanced Solver Options II

## ▸ Direct

- **Used for small problems requiring highest accuracy**
- **Used by default up to 1000 unknowns**

## ▸ Iterative

- **Resolves MoM matrix equation faster than Direct for problems larger than approximately 1000 unknowns**
- **MoM matrix accumulation, memory use, and accuracy levels the same as Direct**
- **Used by default for problems with 1000-5000 unknowns**

## ▸ Fast (SVD FastSolve™)

- **Uses loop tree, iterative solver, Ansoft matrix compression**
- **Far less memory required**
- **Memory compression ratio problem & frequency dependent**
- **Used by default for problems >5000 unknowns**
- **Not efficient for problems <~5000 unknowns**



# Environment Variables

## ▶ **ENSEMBLE\_TRACE\_THICKNESS**

- ▶ Utilized by 2.5D engine only,  $Z_s(t)$
- ▶ Default 17.5um (1/2 oz Cu)
- ▶  $0 < \text{thickness} < 1\text{mm}$
- ▶ Global setting – all trace layers
- ▶ Setting other than default appears in profile

## ▶ **ENSEMBLE\_CPW\_BOTH\_MODES**

- ▶ Set to compute even and odd mode CPW
- ▶ Both CPW slots must be the same width

# **Ensemble™ Fundamentals Remain the Same ...**

**Stay tuned for NextGen !**



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